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(71) Applicant *(for all designated States except US)*: **PHICOM CORPORATION** [KR/KR]; 60-29, Gasan-dong, Geumcheon-gu, Seoul 153-801 (KR).

(72) Inventor; and

(75) Inventor/Applicant *(for US only)*: **LEE, Han-Moo** [KR/KR]; 6-4 Ho, Songjeong-dong 73-763, Seongdong-gu, Seoul 133-160 (KR).

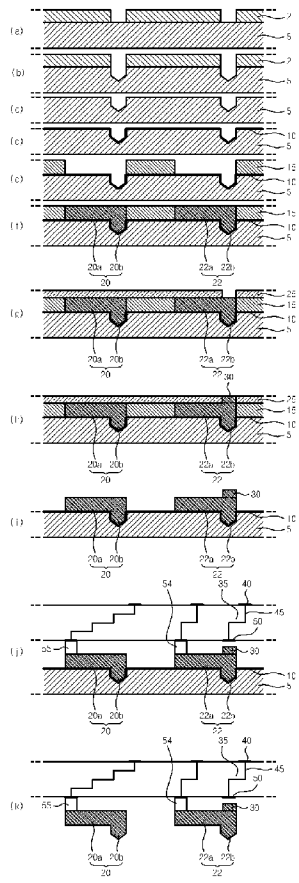
(74) Agents: **KWON, Hyuk-Soo** et al.; 3rd Fl., 827-25, Yeoksam-dong, Kangnam-ku, Seoul 135-080 (KR).

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(54) Title: A PROBE CARD MANUFACTURING METHOD INCLUDING SENSING PROBE AND THE PROBE CARD, PROBE CARD INSPECTION SYSTEM



(57) Abstract: There is provided a method of manufacturing a probe card. A first passivation pattern for implementing a tip portion of an electrical inspection probe and a tip portion of a planarity sensing probe on a sacrificial substrate is formed, and an etching process using the first passivation pattern as an etch mask is performed to form a first trench in the sacrificial substrate. The first passivation pattern is removed, and a second passivation pattern having bar-type first openings exposing the first trench is formed. A conductive material is provided in the openings to form beam portions connected respectively to the tip portions of the inspection and sensing probes, thereby forming the inspection probe and the sensing probe. The beam portions of the inspection and sensing probes are bonded to a multi-layer circuit board. The sacrificial substrate is removed to expose the inspection probe and the sensing probe.

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